

3.2 Field descriptions (cont'd)

Table 3 — Codes for package-specific features

Function (in order of priority)	Code	Subcode	Package-specific feature (relevant dimensions)
Added feature	H A C		Integral heat spreader wholly or partially exposed Stacked package assembly Windowed package for optical devices
Maximum Seated height (profile)	B (blank) L T V W U X	B2 B1 Use above Use below X1 X2 X3 X4	Extra thick (>3.50 mm) Very thick (>2.45 mm and ≤3.50 mm) Thick (>2.45 mm) Standard (>1.70 mm and ≤2.45 mm) Low (>1.20 mm and ≤1.70 mm) Thin (>1.00 mm and ≤1.20 mm) Very thin (>0.80 mm and ≤1.00 mm) Very, very thin (>0.65 mm and ≤0.80 mm) Ultra thin (>0.50 mm and ≤0.65 mm) Extremely thin (≤0.50 mm) Extra-thin (>0.40 mm and ≤0.50 mm) Super-thin (>0.30 mm and ≤0.40 mm) Paper-thin (>0.25 mm and ≤0.30 mm) Die-thin (≤0.25 mm)
Terminal pitch	E		Enlarged (>1.27 mm for DSO, SOJ) Enlarged (>1.00 mm for QFP) Enlarged (>0.100 in for DIP, SIP, PGA) Enlarged (≥1.50 mm for BGA, LGA, CGA)
	(blank)		Standard (>0.070 in and ≤ 0.100 in) for DIP, SIP, PGA) Standard (>0.65 mm and ≤1.27 mm for DSO, SOJ) Standard (>0.50 mm and ≤1.00 mm for QFP) Standard (≥0.40 mm and ≤1.00 mm for LQFP, TQFP) Standard (≥1.00 mm and <1.50 mm for BGA, LGA, CGA)
	S		Shrink (≤0.65 mm for DSO, SOJ) Shrink [≤0.070 in (1.78 mm) for DIP, SIP, PGA]
	F	F1 F2 F3 F4 F5 F6	Fine (≤0.50 mm for QFP, QFN, DSO, SON) Fine (<1.00 mm for BGA, LGA, DSB, WLB) Fine (= 0.80 mm for BGA, LGA, DSB, WLB) Fine (= 0.75 mm for BGA, LGA, DSB, WLB) Fine (= 0.65 mm for BGA, LGA, DSB, WLB) Fine (= 0.50 mm for BGA, LGA, DSB, WLB) Fine (= 0.40 mm for BGA, LGA, DSB, WLB) Fine (= 0.30 mm for BGA, LGA, DSB, WLB)
Other	I R		Interstitial pitch (staggered leads) Rectangular body
NOTE Certain packages (DIP, SIP, PGA) traditionally designed using inch dimensioning may continue to use			

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